

Abstract of the Disclosure:

Two materials with different strength properties are bonded to one another to give a composite, in a mold which serves for shaping. The bond between the two materials may be produced by chemical/physical bonding mechanisms and/or external  
5 profiling, in particular by undercuts. The bonding may be substantially promoted by utilizing the intrinsic heat in one material.

T06070"0E4F0660

WHS:tk - 2763-207-187F//7/5/2001